

ORDER INFORMATION:

CFP-507 - $\frac{X}{a}$ 2- $\frac{WX}{b}$ -D


MATERIAL

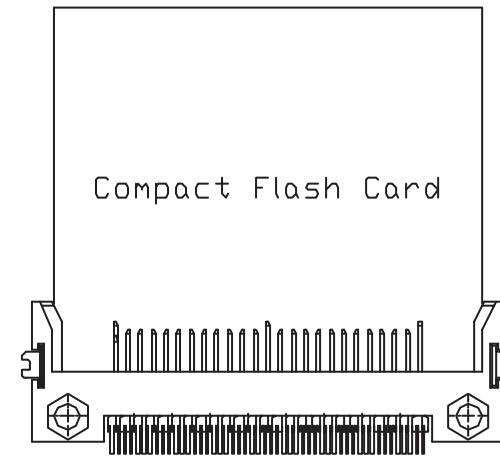
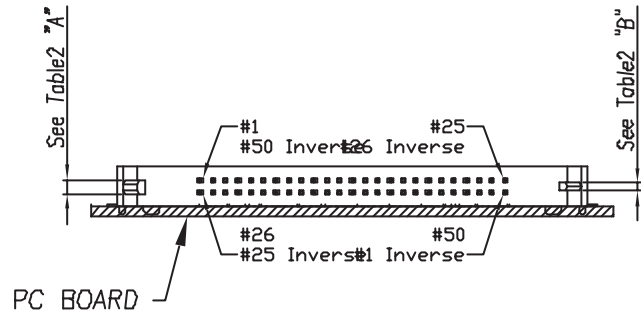
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
 CONTACT: COPPER ALLOY.
 PCD: BRASS.

PLATING

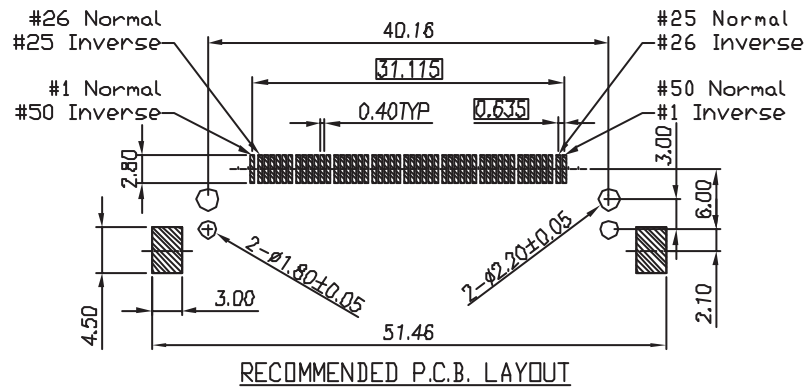
CONTACT: UNDERPLATED: 50 μ " MIN Ni.
 CONTACT AREA: SELECTED GOLD OVER Ni PLATED.
 SOLDER TAIL: 100 μ " MIN Tin OVER Ni PLATED.
 PCD: 100 μ " MIN Tin OVER 50 μ " MIN Ni PLATED.


- a. Contact Area Plating:
 01: G/F Gold Plating
 05: 5 μ " Gold Plating
 15: 15 μ " Gold Plating
- b.
 3 : Normal
 4 : Reverse

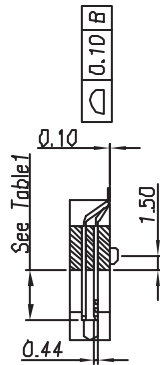
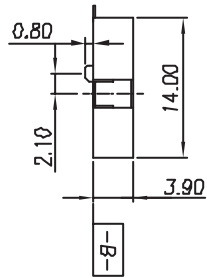
GENERAL TOLERANCE .X \pm 0.30 .XX \pm 0.20 .XXX \pm 0.10	DATE H. D. LI	PART NO CFP-507-X2-WX-D
	DESIGN H. D. LI	TITLE CF CARD CONN. SLIM TYPE
	CHECKED Y. M. LU	
UNIT :mm	APPROVED J. F. KANG	 宏揚精密有限公司 HOJAR PRECISION CO., LTD.



CARD INSERTION



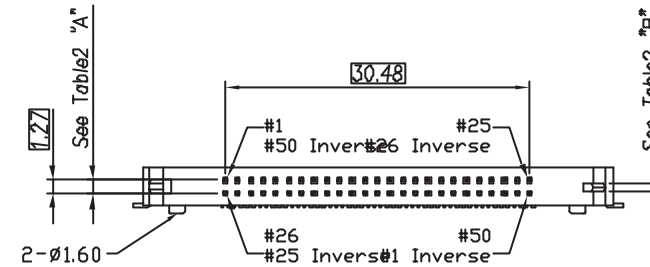
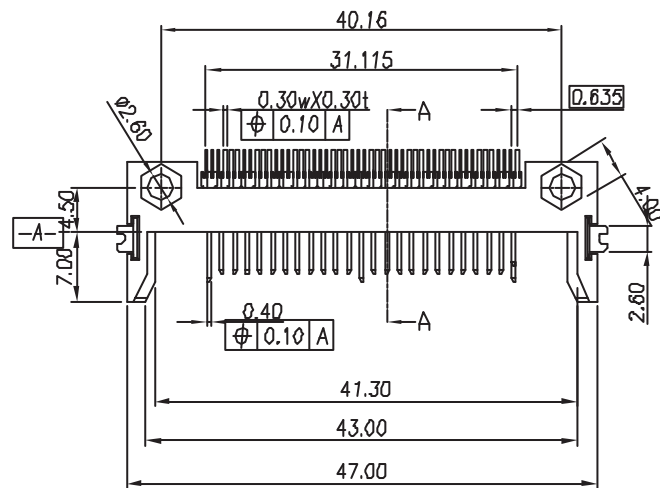
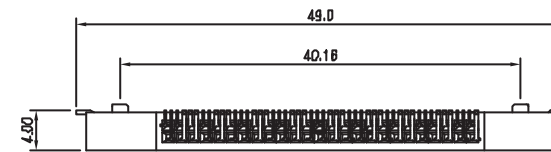
GENERAL TOLERANCE .X ± 0.30 .XX ± 0.20 .XXX ± 0.10	DATE H. D. LI	PART NO CFP-507-X2-WX-D
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SECTION A-A

Pin Type	Interface Dim.	Pin No.
Detect	3.50mm (0.138in)	25,26
General	4.25mm (0.167in)	The Others
Power	5.00mm (0.197in)	01,13,38,50

Type	DIM	A	3
Normal	1.40mm	0.79mm	
Inverse	0.79mm	1.40mm	



GENAL TOLERANCE .X ± 0.30 .XX ± 0.20 .XXX ± 0.10	DATE	H. D. LI	PART NO CFP-507-X2-WX-D
	DESIGN	H. D. LI	
UNIT :mm	CHECKED	Y. M. LU	TITLE CF CARD CONN. SLIM TYPE
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